



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-07-01
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS360AF	HA3E*Z67Q85U	A	Z6IA	2016-07-01
	Amount	UoM	Unit type	ST ECOPACK Grade
	26.40	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFF	1.75X4.7X0.98	N/A	flat	
Comment	Package: SOD128-FLAT NEP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HA3E*Z67Q85U					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	1.109	mg	supplier	die	Silicon (Si)	7440-21-3		1.035	mg	933273	39205
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	8115	341
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	904	38
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1803	76
				supplier	metallization	Nickel (Ni)	7440-02-0		0.007	mg	6312	265
				supplier	metallization	Gold (Au)	7440-57-5		0.006	mg	5410	227
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	8115	341
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	902	38
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1803	74
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	9017	379
				supplier	polymer die coating	Durimide	proprietary		0.027	mg	24346	1023
				Leadframe	Copper and its alloys	9.498	mg	supplier	Leadframe	Copper (Cu)	7440-50-8	
supplier	Leadframe	Iron (Fe)	7439-89-6						0.011	mg	1158	417
supplier	Leadframe	Iron Phosphide (Fe2P)	1310-43-6						0.003	mg	316	114
Leadframe clip	Copper and its alloys	2.531	mg	supplier	Leadframe Clip	Copper (Cu)	7440-50-8		2.467	mg	974714	93447
				supplier	Leadframe Clip	Iron (Fe)	7439-89-6		0.060	mg	23706	2273
				supplier	Leadframe Clip	Zinc (Zn)	7440-66-6		0.003	mg	1185	114
				supplier	Leadframe Clip	Iron Phosphide (Fe2P)	1310-43-6		0.001	mg	395	38
Die Attach	Other organic materials	2.755	mg	JIG R	Solder Paste	Lead (Pb)	7439-92-1	7a-Lead in high me	2.617	mg	949909	99129
				supplier	Solder Paste	Tin (Sn)	7440-31-5		0.138	mg	50091	5227
Encapsulation	Other organic materials	10.211	mg	supplier	Molding Compound	Silica	60676-86-0		6.251	mg	612183	236780
				supplier	Molding Compound	Epoxy Cresol Novolak	29690-82-2		1.682	mg	164724	63712
				supplier	Molding Compound	Metal hydroxide	21645-51-2		1.347	mg	131917	51023
				supplier	Molding Compound	Phenol resin	9003-35-4		0.897	mg	87846	33977
				supplier	Molding Compound	carbon black	1333-86-4		0.034	mg	3330	1288
Connection coating	Other inorganic materials	0.296	mg	supplier	Solder Alloy	Tin	7440-31-5		0.296	mg	1000000	11212